

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF: :  
ROBERT PHILIPPE : ATTN: APPLICATION DIVISION  
SERIAL NO: NEW U.S. PCT APPLN :  
(Based on PCT/FR00/02065)  
FILED: HEREWITH : EXAMINER:  
FOR: METHOD OF FABRICATING :  
THROUGH-CONNECTIONS A  
SUBSTRATE, AND SUBSTRATE  
EQUIPPED WITH SUCH CONNECTIONS

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

Prior to a first examination on the merits, please amend the above-identified  
application as follows:

IN THE CLAIMS

Please cancel Claims 1-10 without prejudice.

Please add new Claims 11-20 as follows:

11. (New) A method of fabricating conducting through-connections between a front  
face and a rear face of a substrate, comprising:  
a) hollowing into the substrate, from the rear-face side, cavities having a depth and a  
cross-section which are defined so as to delimit, by these cavities, studs of defined cross-  
section configured to provide for electrical conduction between the front and rear faces;